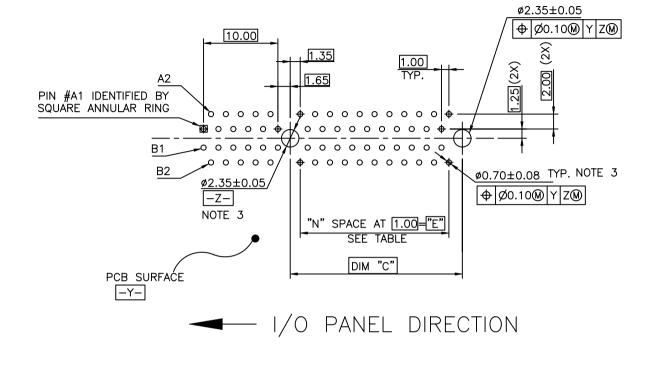


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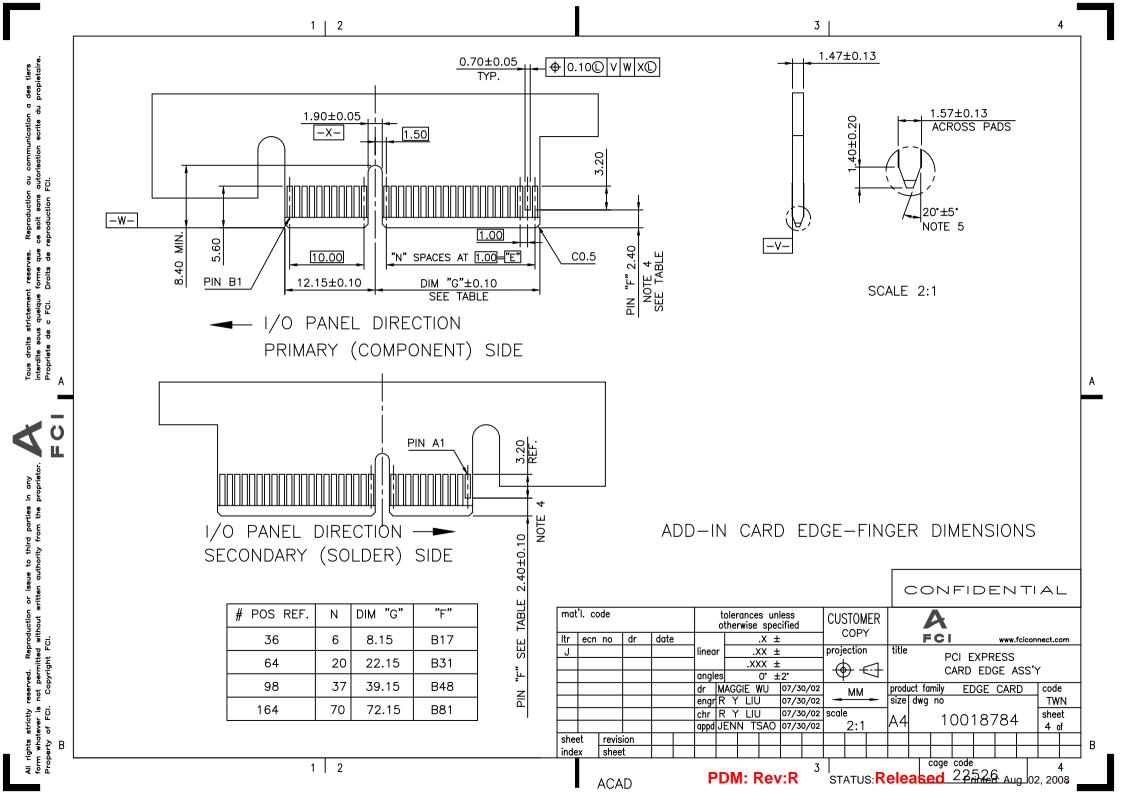


RECOMMENDED FOOTPRINT

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PDM: Rev:R

STATUS: Released 4 Printer Aug 102, 2008



3 NOTES: 1.MATERIAL: HOUSING: NYLON, GLASS FILLED UL94V-0 RATE, SUITABLE FOR WAVE SOLDERING. TERMINAL: COPPER ALLOY DIM "A" DIM "B" DIM "C" "F" # POS REF. CONNECTOR PLATING: 50u" NICKEL UNDERPLATE ALL OVER CONTACT AREA PLATING - SEE PRODUCT NUMBER CODE SOLDER TAIL: TIN/LEAD (90/10) - SEE PRODUCT NUMBER CODE 100u" MIN. OVER 50u" NICKEL 1 PORT 36 6 7.65 25.00 9.15 6.00 METAL BOARD LOCKS: COPPER ALLOY 4 PORT 64 20 21.65 39.00 23.15 20.00 FINISH: 100u" TIN/LEAD (90/10) OVER 50u" NICKEL UNDERPLATE SEE PRODUCT NUMBER CODE 8 PORT 98 37 38.65 56.00 40.15 37.00 2.PRODUCT SPECIFICATION: GS-12-233 3)THE HORIZONTAL AXIS FOR THE HOLE PATTERN IS ESTABLISHED BY 16 PORT 164 70 71.65 89.00 73.15 70.00 A LINE THROUGH THE CENTER OF THE TWO #2.35 HOLES. THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM Z. (4)NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND PIN NUMBERS "F". (5) CHAMFER EDGES MUST BE FREE OF CUTTING BURRS. (6) FREQUENCY & LOCATION AT SUPPLIER DISCRETION. RIDGE MAY BE CONTINUOUS WITH NO BREAKS. 7.RoHS COMPATIBLE PRODUCT SPECIFICATIONS a - PLATING: - "LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um MINIMUM NICKEL UNDERPLATE. b - MANUFACTURING PROCESS COMPATIBILITY - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD. - THE HOUSING WILL WITHSTAND EXPOSURE TO 240°C±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.(For 10018784-X 0 X X X X(X X) options) PRODUCT NUMBER CODE 10018784 -x x x x x x o o LEAD FREE OPTION HOUSING COLOR OPTIONS LEAVE BLANK FOR TERMINAL PLATING 3,4,5 0-WHITE "LF" FOR TERMINAL PLATING OPTION 0.1.2 1-BLACK PACKAGING OPTIONS T-TRAY PACKAGING M-TRAY PACKAGING & MYLAR TAPE FOR PICK-N-PLACE. SEE FIGURE 1 POS OPTIONS PEGS OPTIONS 0 - 360-PLASTIC PEGS 1-64 1-METAL BOARD LOCKS 2-98 3 - 164TERMINAL PLATING OPTIONS TAIL LENGTH OPTIONS 0-50u" Ni UNDERPLATE DIM "D" PCB THICKNESS BOARD LOCKS DIM"G' 30u" Au CONTACT AREA 100u" TIN TAIL AREA ---- COMPATIBLE RoHS 2.30 +0.25 1.56±0.10 1.70±0.15 1-50u" Ni UNDERPLATE 15u" Au CONTACT AREA CONFIDENTIAL $3.10^{+0.25}_{-0.13}$ 100u" TIN TAIL AREA ---- COMPATIBLE RoHS 2.36±0.10 2.50 ± 0.15 2-50u" Ni UNDERPLATE mat'l, code GOLD FLASH CONTACT AREA tolerances unless CUSTOMER 100u" TIN TAIL AREA ---- COMPATIBLE RoHS otherwise specified COPY 3-50u" Ni UNDERPLATE Itr ecn no dr date .x ± FCI www.fciconnect.com 30u" Au CONTACT AREA title projection R linear .XX ± 100u" TIN/LEAD TAIL AREA ---- INCOMPLIANT RoHS PCI EXPRESS .XXX ± 4-50u" Ni UNDERPLATE CARD EDGE ASS'Y 15u" Au CONTACT AREA 0° ±2° angles 100u" TIN/LEAD TAIL AREA ---- INCOMPLIANT ROHS dr MAGGIE WU 07/30/02 product family EDGE CARD code MM 5-50u" Ni UNDERPLATE size dwg no engr R Y LIU 07/30/02 TWN GOLD FLASH CONTACT AREA chr R Y LIU 07/30/02 scale sheet 100u" TIN/LEAD TAIL AREA ---- INCOMPLIANT RoHS 10018784 appd JENN TSAO 07/30/02 1:1 5 of sheet revision sheet index

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